



## 样品承认书

SAMPLE APPROVAL SHEET

CUSTOMER: \_\_\_\_\_

SIZE UP: \_\_\_\_\_

声表面谐振器

Volume: \_\_\_\_\_

R315M

NUMBER: \_\_\_\_\_

SMD3030mm

DATE: \_\_\_\_\_

承認後請寄回一份

PLS SEND BACK ONE COPY TO US AFTER YOUR APPROVAL

承認結果 CONCLUSION	客戶簽名 SIGNATURE	客戶承認章 STAMP	日期 DATE	備注 REMARK
合格 ACCEPT				
不合格 REJECT				

制表

刘小姐

审核: \_\_\_\_\_

(公章)

尊敬的客户: 请您抽出一点时间, 在7-10个工作日内将承认书回签, 若未回签, 以视默认. 谢谢合作!

# TH R315M声表面谐振器 SMD3030mm

This specification shall cover the characteristics of 1-port SAW resonator with R315M used for remote-control security.

## 2. Electrical Specification

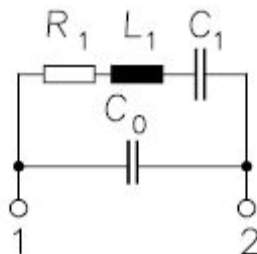
### 2.1 Maximum Rating

DC Voltage VDC	10V
AC Voltage Vpp	10V 50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
Source Power	0dBm

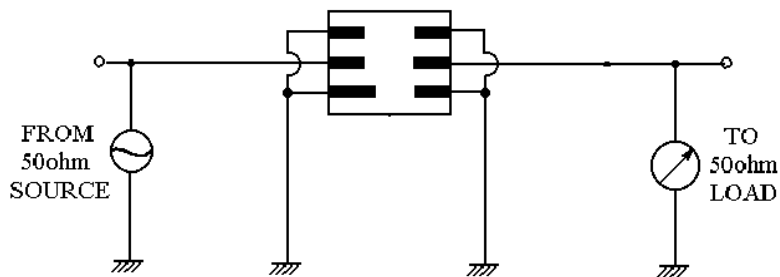
### 2.2 Electronic Characteristics

Item	Unites	Minimum	Typical	Maximum	
Center Frequency	MHz	314.925	315.000	315.075	
Insertion Loss	dB		1.4	1.9	
Quality Factor	Unload Q	8000	12800		
	50Ω Loaded Q	1000	2000		
Temperature Stability	Turnover Temperature	°C	10	25	40
	Freq.temp.Coefficient	ppm/°C	0.032		
Frequency Aging		ppm/yr	<±10		
DC. Insulation Resistance	MΩ	1.0			
RF Equivalent RLC Model	Motional Resistance R1	Ω	17.6		
	Motional Inductance L1	μH	118		
	Motional Capacitance C1	fF	2.16		
Transducer Static Capacitance C0		pF	2.13		

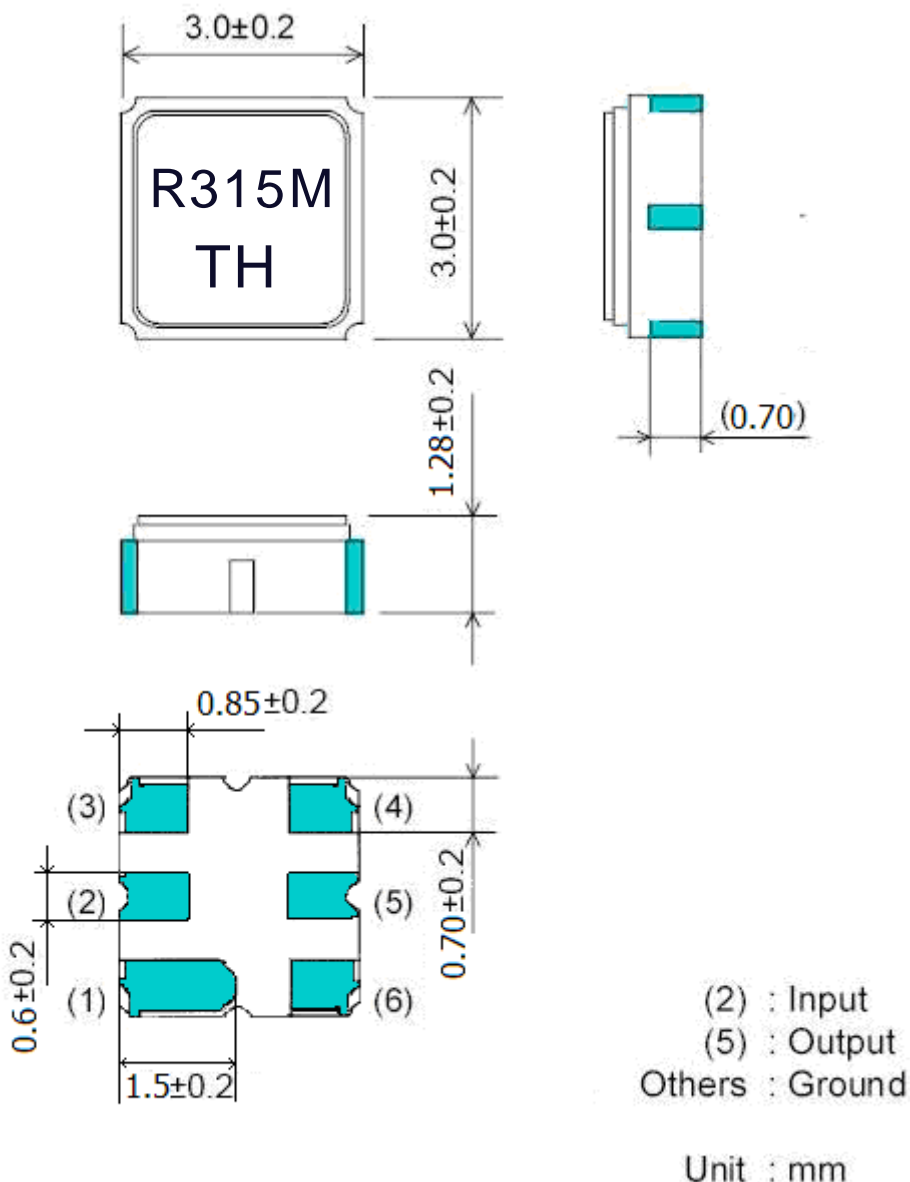
### 2.3 Equivalent LC Model



### 3. Test Circuit



### 4. Dimension



1. TH: Manufacture's logo
2. R315M : Model code

## 5. Environment Characteristic

### 5-1 Thermal Shock:

The components shall remain within the electrical specifications after being kept at the condition of heat cycle conditions:  $T_A = -40^{\circ}\text{C} \pm 3^{\circ}\text{C}$ ,  $T_B = 85^{\circ}\text{C} \pm 2^{\circ}\text{C}$ ,  $t_1 = t_2 = 30\text{min}$ , switch time  $\leq 3\text{min}$  & cycle time : 100 times, recovery time:  $2\text{h} \pm 0.5\text{h}$ .

### 5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at  $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for  $10 \pm 1$  sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2.2.

### 5-3 Solder ability

Submerge the device terminals into the solder bath at  $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2.2

### 5-4 The Temperature Storage:

5.3.1 High Temperature Storage: The components shall remain within the electrical specifications after being kept at the  $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$  for  $96\text{h} \pm 4\text{h}$ , recovery time :  $2\text{h} \pm 0.5\text{h}$ .

5.3.2 Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the  $-40^{\circ}\text{C} \pm 3^{\circ}\text{C}$  for  $96\text{h} \pm 4\text{h}$ , recovery time :  $2\text{h} \pm 0.5\text{h}$ .

### 5-5 Humidity test:

The components shall remain within the electrical specifications after being kept at the condition of ambient temperature  $60^{\circ}\text{C} \pm 2^{\circ}\text{C}$ , and 90~96% RH for  $96\text{h} \pm 4\text{h}$ .

### 5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m for 3 times. The resonator shall fulfill the specifications in 2.2.

### 5-7 Vibration

Subject the device to the vibration for 2 hour each in X, Y and Z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The resonator shall fulfill the specifications in 2.2.

## 6. Remark

### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 6.3 Soldering

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Only leads of component may be soldered. Please avoid soldering another part of component.

## 7. Packing

### 7.1 Dimensions

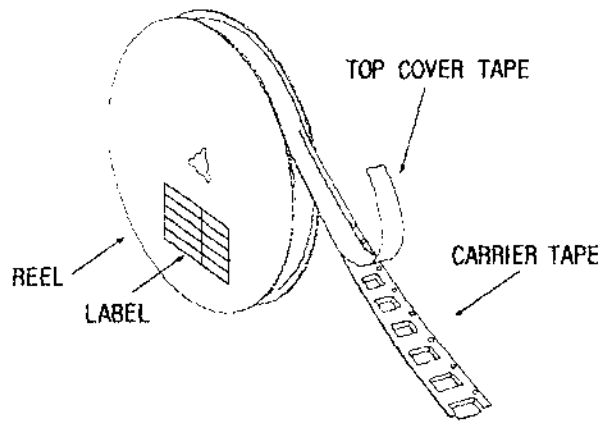
- (1) Carrier Tape: Figure 1
- (2) Reel: Figure 2
- (3) The product shall be packed properly not to be damaged during transportation and storage.

### 7.2 Reeling Quantity

- 1000 pcs/reel 7"
- 3000 pcs/reel 13"

### 7.3 Taping Structure

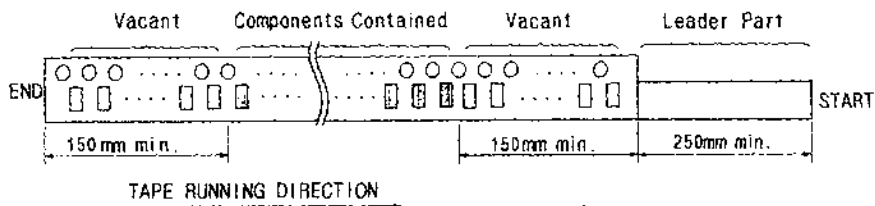
- (1) The tape shall be wound around the reel in the direction shown below.



- (2) Label

Device Name	
User Product Name	
Quantity	
Lot No.	

- (3) Leader part and vacant position specifications.

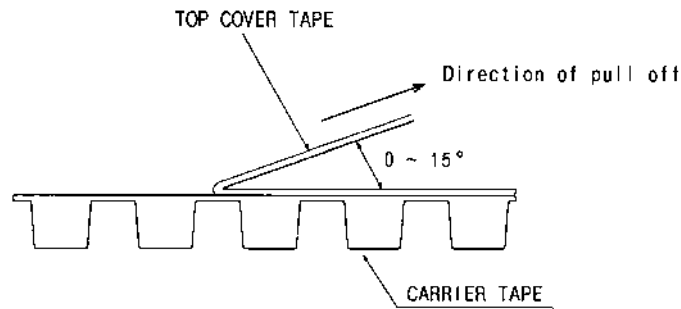


## 8. Tape Specifications

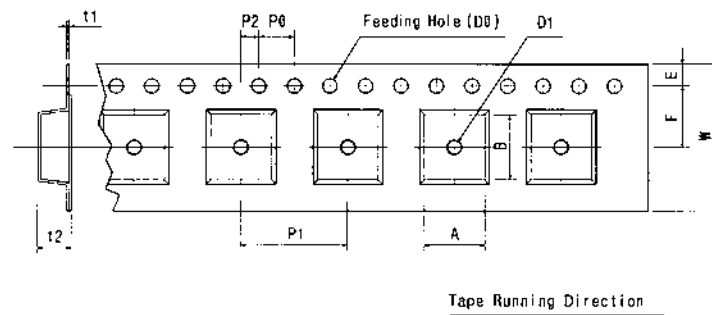
8.1 Tensile Strength of Carrier Tape: 4.4N/mm width

8.2 Top Cover Tape Adhesion (See the below figure)

- (1) pull off angle: 0~15°
- (2) speed: 300mm/min.
- (3) force: 20~70g



[Figure 1] Carrier Tape Dimensions

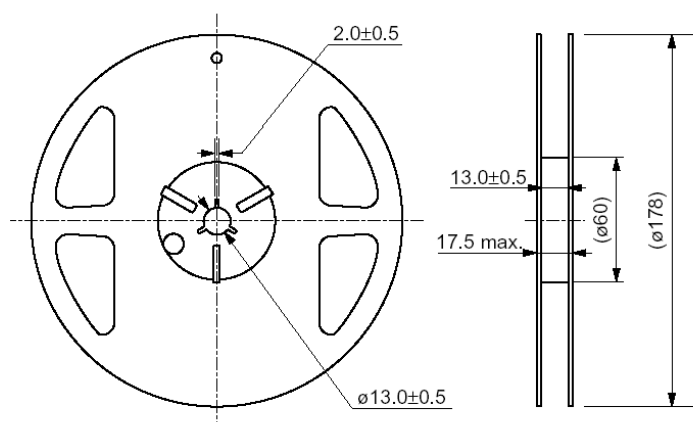


[Unit: mm]

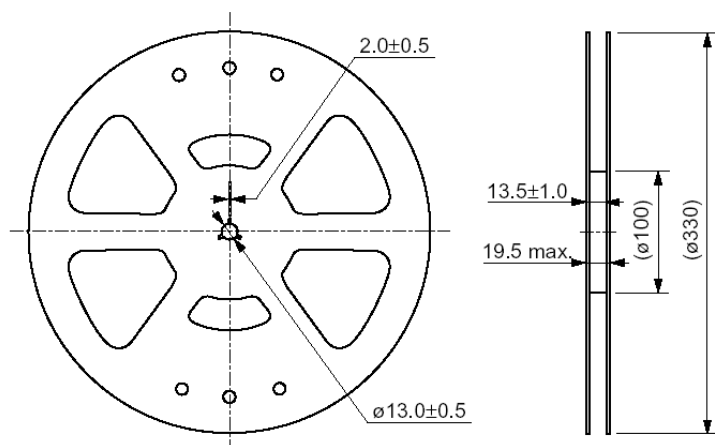
W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
12.0	5.5	1.75	4.0	4.0	2.0	Ø1.5	Ø1.0	0.3	1.25	3.3±	3.3±
±0.3	±0.05	±0.1	±0.1	±0.1	±0.05	±0.1	±0.25	±0.05	±0.1	0.1	0.1

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[Figure 2] Reel Dimensions



ø178 Reel Dimension (in mm)



ø330 Reel Dimension (in mm)